

**IBIS Open Forum Minutes**

Meeting Date: **November 14, 2018**

Meeting Location: **Shanghai, China**

**VOTING MEMBERS AND 2018 PARTICIPANTS**

ANSYS Curtis Clark, Miyo Kawata

Applied Simulation Technology (Fred Balistreri)

Broadcom (Yunong Gan)

Cadence Design Systems Brad Brim, Ken Willis, Ambrish Varma, Zhen Mu

Morihiro Nakazato, Jinsong Hu\*, Skipper Liang\*

Zuli Qin\*, Haisan Wang\*, Hui Wang\*, Yitong Wen\*

Clark Wu\*, Zhangmin Zhong\*

Cisco Systems Stephen Scearce, Cassie Yan, Baosh Xu

CST Stefan Paret

Ericsson Anders Ekholm\*, Zilwan Mahmod\*, Guohua Wang

Wenyan Xie

GLOBALFOUNDRIES Steve Parker

Huawei Technologies (Hang (Paul) Yan)

IBM Greg Edlund, Luis Armenta, Hubert Harrer

Michael Cohen

Infineon Technologies AG (Christian Sporrer)

Intel Corporation Hsinho Wu, Michael Mirmak, Nilesh Dattani

Fernando Mendoza Hernandez, Varun Gupta

Subas Bastola, Hansel Dsilva, Gianni Signorini

Kai Yuan\*

IO Methodology Lance Wang\*

Keysight Technologies Radek Biernacki, Ming Yan, Heidi Barnes

Pegah Alavi, Toshinori Kageura, Satoshi Nakamizo

Umekawa Mitsuharu

Maxim Integrated Joe Engert, Yan Liang

Mentor, A Siemens Business Arpad Muranyi, Weston Beal, Raj Raghuram

Carlo Bleu, Mikael Stahlberg, Yasushi Kondou

Vladimir Dmitriev-Zdorov, Nitin Bhagwath

Kazuhiro Kadota, Terence Guo\*

Micron Technology Randy Wolff, Justin Butterfield

Micron Memory Japan Masayuki Honda, Tadaaki Yoshimura, Toshio Oki

Mikio Sugawara

NXP (John Burnett)

Raytheon Joseph Aday

SiSoft Mike LaBonte\*, Walter Katz, [Todd Westerhoff]

Synopsys Ted Mido, Adrien Auge, Scott Wedge, Xuefeng Chen\*

Jinghua Huang\*, Yuyang Wang\*

Teraspeed Labs Bob Ross

Xilinx Ravindra Gali

ZTE Corporation Shunlin Zhu\*, Liqiang Meng\*, Yonghui Ren\*, Bi Yi\*

Zuken Michael Schaeder, Takayuki Shiratori

**OTHER PARTICIPANTS IN 2018**

A&D Print Engineering Co. Ryu Murota

Abeism Corporation Nobuyuki Kiyota, Noboru Kobayashi

Alpine Electronics Norio Mashiko

AMD Japan Tadashi Arai

Apollo Giken Co. Naoya Iisaka, Satoshi Endo

Avnet Shinya Ishizuka

BasiCAE Kiki Li\*, Darcy Liu\*, Linda Zhang\*

Canon Components Takeshi Nagata

Canon Syoji Matsumoto, Yusuke Matsudo, Manabu Sakakibara

Tadashi Aoki, Hitoshi Matsuoka, Ryuta Kusaka

Masaaki Ohishi, Satoru Ishikawa

Casio Computer Co. Yasuhisa Hayashi

Celestica Sophia Feng\*, Bowen Shi\*

CMK Products Corp. Hiroyasu Miura

Credo Anyun Liu\*

Cybernet Systems Takayuki Tsuzura

Denso Corp. Yukiya Fukunaga

Eizo Corp. Tokimitsu Eso

Finnhan Yuan Xu\*

Fuji Xerox Manufacturing Co. Rumi Maeda

Fujitsu Advanced Technologies Tendo Hirai, Kumiko Teramae, Hidenobu Shiihara

Fujitsu Interconnect Technologies Masaki Kirinaka, Akiko Tsukada

Fujitsu Ltd. Takashi Kobayashi

Fujitsu Optical Components Masaki Kunii

Gifu University Toshikazu Sekine

Global Unichip Japan Masafumi Mitsuishi

Google Zhiping Yang

Hamamatsu Photonics Akihiro Inoguchi, Shigenori Fujita, Hidetoshi Nakamura

Haskware David Banas

Hitachi ULSI Systems Co. Sadahiro Nonoyama

Hitachi Ltd. Yasuhiro Ikeda

Hoei Co. Tatsuya Chiba

Huawei Technologies Haiping Cao\*, Longfang Lv\*, Shengli (Victory) Wang\*

Hang (Paul) Yan\*, Chen (Jeff) Yu\*, Zhengyi Zhu\*

Peng Huang\*

IB-Electronics Matsumuro Makoto

Independent Hiroshi Ishikawa, Fumiyo Kawafuji

Japan Radio Co. Hiroto Katakura

JEITA Yukio Masuko

John Baprawski, Inc. John Baprawski

JVC Kenwood Corp. Yasutoshi Ojima, Masayuki Kurihara

KEI Systems Shinichi Maeda

Keihin Corp. Takayuki Ota

Lapis Semiconductor Co. Satoshi Tachi

Lattice Semiconductor Dinh Tran, Maryam Shahbazi

Lenovo Mark Zheng\*

Marvell Jianping Kong\*, Fang Lv\*, Banglong Qian\*

Songjie (Jacky) Wang\*, Liang Wu\*

Megachips Corp. Tomochika Kitamura

Mitsubishi Electric Corp. Yusuke Suzuki

Mobile Techno Corp. Kazuhiro Kamegawa

Molex Japan Nobumasa Motohashi

Murata Manufacturing Co. Kazutaka Mukaiyama

NEC Magnus Communications Toshio Saito

New H3C Group Xinyi Hu\*, Zixiao Yang\*

Nikon Corp. Manabu Matsumoto

Oki Electric Industry Co. Kenichi Saito

OmniVision Sirius Tsang

Panasonic Corp. Minori Harada, Tomohiro Tsuchiya, Naoyuki Aoki

Atsushi Nakano

Panasonic Industrial Devices, Kazuki Wakabayashi

Systems and Technology Co.

Politecnico di Milano Flavia Grassi, Xinglong Wu

Politecnico di Torino Tommaso Bradde, Marco De Stefano, Paulo Manfredi

Riccardo Trinchero, Stefano Grivet-Talocia

PWB Corp. Toru Ohisa

Qualcomm Kevin Roselle, Tim Michalka, Zhiguang Li\*

Renesas Electronics Corp. Masayasu Koumyou, Kazunori Yamada, Kenzo Tan

Hiroyoshi Kuge, Masato Suzuki

Ricoh Company Kazuki Murata, Yasuhiro Akita, Kazumasa Aoki

Toshihiko Makino, Koji Kurose

RITA Electronics Ltd. Kenichi Higashiura, Hiroyuki Motoki

Rohm Co. Noboru Takizawa, Ryosuke Inagaki, Nobuya Sumiyoshi

Ryosan Co. Takahiro Sato, Takumi Ito

SAE ITC (Jose Godoy)

Sanwa Denki Kogyo Co. Yutaka Takasaki

Shanghai IC R&D Center (ICRD) Huijie Yan\*, Hailing Yang\*

Shanghai Zhaoxin Semiconductor Chuanyu (Liam) Li\*

Shinko Electric Industries Co. Takumi Ikeda

Signal Metrics Ron Olisar

Silvaco Japan Co. Yoshihiko Yamamoto, Kaoru Kashimura

SMK Corp. Norihide Taguchi

Socionext Megumi Ono, Yumiko Sugaya, Mitsuhiro Tomita

Katsuya Ogata, Yoshihiko Sumimoto, Yuji Nakagawa

Takashi Araki

Sohwa & Sophia Technologies Tomoki Yamada

Sony Global Manufacturing & Takashi Mine, Toshio Murayama, Taichi Hirano

Operations Corp. Takashi Mizoroki

Sony LSI Design Toru Fujii

Sony Semiconductor Solutions Takeshi Ogura

SPISim Wei-hsing Huang\*, Wei-Kai Shih

Stanford University Tom Lee

STMicroelectronics Aurora Sanna, Olivier Bayet

Syswave Kazuo Ogasawara

TDK Corp. Kotaro Suzuki

Technopro Design Co. Mai Fukuoka

Teledyne LeCroy Denny Li\*, Nan Son\*, Suping Wu\*, Sherry\*

Telepower Kenji Kobayashi

TFF Tektronix Co. Katsuhiko Suzuki

Thine Electronics Takafumi Nakamori

Tomen Devices Corp. Kinji Mitani

Toshiba Corp. Yasuki Torigoshi

Toshiba Development & Nobuyuki Kasai

Engineering Corp.

Toshiba Electronic Devices & Atsushi Tomishima, Yasunobu Umemoto

Storage Corp. Yoshinori Fukuba, Hitoshi Imi, Motochika Okano

Tetsuya Nakamura

Toshiba Memory Corp. Masato Kanie, Takayuki Mizogami

Toshiba Memory Systems Co. Eiji Kozuka, Tomomichi Takahashi

Toshiba Microelectronics Corp. Jyunya Masumi

Unisoc Junyong Deng\*, Nikki Xie\*

Université de Bretagne Occidentale Mihai Telescu, Charles Canaff

University of Illinois José Schutt-Aine  
University of Siegen Elmar Griese  
University of Technology Hamburg Torben Wendt  
Xpeedic Suxiang Zhou\*

Xrossvate Toshiyuki Kaneko

Yamaha Corp. Tetsuya Kakimoto

Zhejiang Uniview Technologies Fang Yang\*

Zheijiang YUSHI Technology E. Deng\*

In the list above, attendees at the meeting are indicated by \*. Principal members or other active members who have not attended are in parentheses. Participants who no longer are in the organization are in square brackets.

**UPCOMING MEETINGS**

The bridge numbers for future IBIS teleconferences are as follows:

Date Meeting Number Meeting Password

November 16, 2018 Asian IBIS Summit (Taipei) – no teleconference

November 30, 2018 624 227 121 IBISfriday11

For teleconference dial-in information, use the password at the following website:

<http://tinyurl.com/y7yt7buz>

All teleconference meetings are 8:00 a.m. to 9:55 a.m. US Pacific Time. Meeting agendas are typically distributed seven days before each Open Forum. Minutes are typically distributed within seven days of the corresponding meeting.

NOTE: "AR" = Action Required.

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**OFFICIAL OPENING**

The Asian IBIS Summit took place on Wednesday, November 14, 2018 at the Parkyard Hotel in Shanghai. About 58 people representing 25 organizations attended.

The notes below capture some of the content and discussions. The meeting presentations and other documents are available at:

<http://www.ibis.org/summits/nov18b/>

Mike LaBonte opened the summit by welcoming everyone and thanking primary sponsor Huawei. He invited Paul Han of Huawei to give a welcome address, which was followed by Mike's welcome address. Each emphasized the importance of IBIS to the industry. Mike also thanked sponsors Mentor, a Siemens Business, Synopsys, Teledyne LeCroy, and ZTE Corporation. He noted that minutes of the meeting would be posted. There would be two breaks for refreshments and vendor interaction, and free lunch.

**IBIS UPDATE**

Mike LaBonte (SiSoft, USA)

The status and activities of the IBIS Open Forum were described. Mike showed the progress on development of the IBIS 7.0 specification, which he estimated might be ratified in March of 2019, if all goes well. Mike noted that few BIRDs were currently in the pipeline for further development, encouraging the audience to consider submitting their own ideas for IBIS. He planned to give a short walk-through of the BIRD submission and adoption process during final discussion, if time would permit.

**HOW TO FIX DDR4 SIGNAL INTEGRITY ISSUE ABOUT “PIN” AND “DIE”**

Liqiang Meng, Shunlin Zhu (ZTE Corporation, PRC)

[Presented by Liqiang Meng (ZTE Corporation, PRC)]

Liqiang gave an overview of trends in the evolution from DDR4 to DDR5. He showed the relationship between [Package] and [Pin] package model data in IBIS, noting that only [Package] has typ/min/max data. He then explained the Si\_location and Timing\_location subparameters of [Component]. Liqiang showed the differences between pin and die location eye diagrams for both read and cmd operations. As expected, setting package RLC to zero results in identical die and pin waveforms. At 667Mbps, using an equivalent transmission line gave results similar to the lumped RLC model, at the die. At 3200Mbps, the lumped RLC package model appears to give distorted results. Replacing the single section lumped RLC with an n-section distributed RLC produced results that compared well with the transmission line model. Recommendations regarding the next generation of DDR were made for system designers, model creators, and EDA tool vendors.

There was some discussion from the audience about how IBIS already supported most of the recommendations for chip vendors, but there were questions about how PDN analysis would be incorporated, especially if IBIS-AMI models were used.

**MODEL CORRELATION FOR IBIS-AMI**

Wenyan Xie\*, Guohua Wang\*, David Zhang\*, Anders Ekholm\*\* (Ericsson, \*PRC, \*\*Sweden)

[Presented by Wenyan Xie (Ericsson, PRC)]

Step by step procedures were outlined for correlating both TX and RX IBIS-AMI models. Correlation results for a TX testcase were shown. For the RX it is a challenge to measure the waveform at the latch, which is not physically exposed. Some SerDes buffers have the ability to measure internally and report accumulated results, but it is difficult to use that with accuracy. Correlation results for an RX were shown. Feature Selective Validation (FSV) was recommended over Figure of Merit (FOM), but FSV should have more metrics and they should be carefully weighted. It was also recommended that IBIS add a statistical distribution representation for data, replacing typ/min/max corners. Experiments showed that a simulator would use [Pin] RLC only to override the typ corner of [Package] data, but [Package] values would be used, if present, for min and max simulations.

A question was asked about how measurements can be made with sufficient accuracy at GHz frequencies. A number of laboratory techniques are required to improve accuracy, and careful attention must be paid.

**SI TEST AND SIMULATION CORRELATION OF 56G PAM4 EYE DIAGRAM FOR 400G SWITCH**

Bowen Shi, Sophia Feng (Celestica, PRC)

[Presented by Bowen Shi (Celestica, PRC)]

Bowen gave an overview of PAM4 signaling. Three channel topologies were tested, comparing simulations to measurements. Frequency domain characterizations of the three testcases showed observable differences between the topologies. Eye widths and heights were compared. In all three cases, simulation results were optimistic, compared to measurement. Further studies to improve accuracy were planned. A question was asked about the suitability of the simulation results for design sign-off. Simulations were being used to determine the trends of design choices, with previous results used as a reference.

**A PRACTICAL METHODOLOGY FOR SERDES DESIGN**

Amy Zhang\*, Guohua Wang\*, David Zhang\*, Zilwan Mahmod\*, Anders Ekholm\*\* (Ericsson, \*PRC, \*\*Sweden)

[Presented by Anders Ekholm (Ericsson, Sweden)]

Analyzing a SerDes channel to find the best case operation involves not only many combinations of driver and receiver settings, but also a significant number of interconnect characteristics that must be explored under typ/min/max conditions. Simulating 1 million bits across all possible variations for one example would take 506.25 days. The challenge is to make satisfactory design decisions without running many simulations. Ideally, we would create an equation that quickly models system performance, given all of the system condition inputs that can vary. This can be done using Design of Experiments (DOE) methods to statistically sample the parameter space, producing a Response Surface Model (RSM) using relatively few simulations. A CEI-28g example was shown, with the quality of the RSM fit evaluated. Sensitivity analysis was used to assign a different sampling distribution to each factor. Millions of conditions were then evaluated very quickly. Increasingly, we will find that the best/worst case analysis supported by typ/min/max data will not suffice for design closure. Adding an option for IBIS-AMI to represent a full distribution of data would help with DOE analysis, and would allow for predicting performance confidence intervals.

**STUDY OF DDR ASYMMETRIC RT/FT IN EXISTING IBIS-AMI FLOW**

Wei-kai Shih\*, Wei-hsing Huang\*\* (SPISim, \*Japan, \*\*USA)

[Presented by Wei-hsing Huang (SPISim, USA)]

Wei-hsing described how statistical and time domain IBIS-AMI flows worked. For asymmetric rise/fall, Wei-kai described a method for deriving a fall edge from the rise edge, or vice-versa, using a transfer function. He noted it would still be necessary for IBIS-AMI to know the common mode DC offset for single-ended signals. Wei-kai showed example pseudo-code for the transfer function to recover a fall response from the rise response. This could be used to construct eye diagrams with rise/fall asymmetry. A recursive algorithm for calculating eye PDF with asymmetric rise/fall was described. Simulating bit-by-bit with Tx and Rx AMI\_GetWave should work well, but there would be glitches if convolution was involved at the Rx. Pseudo-code for the AMI\_GetWave process was shown.

**CHARACTERIZING AND MODELING OF A CLAMPED NON-LINEAR CTE/AGC**

Skipper Liang (Cadence Design Systems, ROC)

Skipper summarized his 2017 presentation describing a Thevenin equivalent circuit method for characterizing a Continuous Time Equalizer (CTE). The Device Under Test (DUT) could include an Automatic Gain Control (AGC), as long as the condition of linearity was met. The technique involved scaling voltages, so it was important that the DUT have the same characteristics at any voltage, since scaled results would be normalized to actual. In reality, clamping diodes were usually present, causing non-linear effects. One approach is to use a small signal input of 20mV, which captures the high frequency behavior well, but misses the DC behavior. The large signal approach would be to use a 100mV input, but that fails to capture the high frequency response while successfully capturing the DC behavior. To produce a single model that performs well in all cases, a model was constructed in which separate code blocks captured the small signal and large signal behaviors. A method to find the linear voltage range was described. It was found that a hyperbolic tangent function could be used to model the non-linear behavior of clamping diodes, and iterating to find the best coefficients would yield acceptable results for mapping input voltage to output voltage. This was suitable for use in AMI\_GetWave. However, the frequency response of the hyperbolic tangent function model could not be directly derived, because the function fails one of the criteria to be Fourier transformable. A solution to that involved using an equivalent hyperbolic cosecant function to derive the Fourier transform, for use in statistical analysis. Two examples using CTE and AGC were shown, each with good correlation to measurement.

**OPEN DISCUSSION**

During the time for open discussion, Mike LaBonte showed the IBIS website to explain the process by which the IBIS specification is developed. BIRD documents are written by people from one or more organizations using a template, and submitted to the IBIS Chair. Often there are multiple authors, from different companies. The BIRD includes a statement of the issue to be addressed, particular requirements for the solution, and proposed changes to the current IBIS specification to meet the requirements. Anyone may submit a BIRD, but only official IBIS members may vote. The BIRD is discussed in meetings, sometimes over an extended period, and finally a vote to accept it is taken in an IBIS Open Forum meeting. If it passes, the BIRD eventually will be incorporated into a future IBIS specification produced by the IBIS Editorial Task Group.

**CLOSING REMARKS**

Mike LaBonte closed the summit, thanking the sponsors, the authors and presenters, and all participants. He encouraged all to consider proposing their ideas for IBIS through the BIRD process. The summit was adjourned.

**NEXT MEETING**

The next IBIS Open Forum teleconference meeting will be held on November 30, 2018. The following IBIS Open Forum teleconference meeting is tentatively scheduled on December 21, 2018.

The Asian IBIS Summit in Taipei will be held November 16, 2018. No teleconference will be available for the Summit meeting.

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**NOTES**

IBIS CHAIR: Mike LaBonte

[mlabonte@](mailto:mlabonte@)sisoft.com

IBIS-AMI Modeling Specialist, SiSoft

6 Clock Tower Place, Suite 250

Maynard, MA 01754

VICE CHAIR: Lance Wang (978) 633-3388

[lwang@iometh.com](mailto:lwang@iometh.com)

President/CEO, IO Methodology, Inc.

PO Box 2099

Acton, MA 01720

SECRETARY: Randy Wolff (208) 363-1764

[rrwolff@micron.com](mailto:rrwolff@micron.com)

Principal Engineer, Silicon SI Group Lead, Micron Technology, Inc.

8000 S. Federal Way

P.O. Box 6, Mail Stop: 01-711

Boise, ID 83707-0006

TREASURER: Bob Ross (503) 246-8048

[bob@teraspeedlabs.com](mailto:bob@teraspeedlabs.com)

Engineer, Teraspeed Labs

10238 SW Lancaster Road

Portland, OR 97219

LIBRARIAN: Anders Ekholm (46) 10 714 27 58, Fax: (46) 8 757 23 40

[ibis-librarian@ibis.org](mailto:ibis-librarian@ibis.org)

Digital Modules Design, PDU Base Stations, Ericsson AB

BU Network

Färögatan 6

164 80 Stockholm, Sweden

WEBMASTER: Mike LaBonte

[mlabonte@](mailto:mikelabonte@eda.org)sisoft.com

IBIS-AMI Modeling Specialist, SiSoft

6 Clock Tower Place, Suite 250

Maynard, MA 01754

POSTMASTER: Curtis Clark

[curtis.clark@ansys.com](mailto:curtis.clark@ansys.com)

ANSYS, Inc.

150 Baker Ave Ext

Concord, MA 01742

This meeting was conducted in accordance with ANSI guidance.

All inquiries may be sent to [info@ibis.org](mailto:info@ibis.org). Examples of inquiries are:

* To obtain general information about IBIS.
* To ask specific questions for individual response.
* To subscribe to the official [ibis@freelists.org](mailto:ibis@freelists.org) and/or [ibis-users@freelists.org](mailto:ibis-users@freelists.org) email lists (formerly [ibis@eda.org](mailto:ibis@eda.org) and [ibis-users@eda.org](mailto:ibis-users@eda.org)).
* To subscribe to one of the task group email lists: [ibis-macro@freelists.org](mailto:ibis-macro@freelists.org), [ibis-interconn@freelists.org](mailto:ibis-interconn@freelists.org), or [ibis-quality@freelists.org](mailto:ibis-quality@freelists.org).
* To inquire about joining the IBIS Open Forum as a voting Member.
* To purchase a license for the IBIS parser source code.
* To report bugs or request enhancements to the free software tools: ibischk6, tschk2, icmchk1, s2ibis, s2ibis2 and s2iplt.

The BUG Report Form for ibischk resides along with reported BUGs at:

<http://www.ibis.org/bugs/ibischk/>   
[http://www.ibis.org/ bugs/ibischk/bugform.txt](http://www.ibis.org/%20bugs/ibischk/bugform.txt)

The BUG Report Form for tschk2 resides along with reported BUGs at:

<http://www.ibis.org/bugs/tschk/>   
<http://www.ibis.org/bugs/tschk/bugform.txt>

The BUG Report Form for icmchk resides along with reported BUGs at:

<http://www.ibis.org/bugs/icmchk/>   
<http://www.ibis.org/bugs/icmchk/icm_bugform.txt>

To report s2ibis, s2ibis2 and s2iplt bugs, use the Bug Report Forms which reside at:

<http://www.ibis.org/bugs/s2ibis/bugs2i.txt>   
<http://www.ibis.org/bugs/s2ibis2/bugs2i2.txt>   
<http://www.ibis.org/bugs/s2iplt/bugsplt.txt>

Information on IBIS technical contents, IBIS participants and actual IBIS models are available on the IBIS Home page:

<http://www.ibis.org/>

Check the IBIS file directory on ibis.org for more information on previous discussions and results:

<http://www.ibis.org/directory.html>

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**SAE STANDARDS BALLOT VOTING STATUS**

|  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- |
| **Organization** | **Interest Category** | **Standards Ballot Voting Status** | **October 12, 2018** | **November 2, 2018** | **November 12, 2018** | **November 14, 2018** |
| ANSYS | User | Active | X | X | X | - |
| Applied Simulation Technology | User | Inactive | - | - | - | - |
| Broadcom Ltd. | Producer | Inactive | - | - | - | - |
| Cadence Design Systems | User | Active | X | X | X | X |
| Cisco Systems | User | Inactive | - | - | - | - |
| CST | User | Inactive | - | - | - | - |
| Ericsson | Producer | Active | - | X | X | X |
| GLOBALFOUNDRIES | Producer | Inactive | X | X | - | - |
| Huawei Technologies | Producer | Inactive | - | - | - | - |
| IBM | Producer | Inactive | - | X | - | - |
| Infineon Technologies AG | Producer | Inactive | - | - | - | - |
| Intel Corp. | Producer | Active | X | X | - | X |
| IO Methodology | User | Inactive | X | - | - | X |
| Keysight Technologies | User | Active | X | X | X | - |
| Maxim Integrated | Producer | Inactive | - | - | - | - |
| Mentor, A Siemens Business | User | Active | X | X | X | X |
| Micron Technology | Producer | Active | X | X | X | - |
| NXP | Producer | Inactive | - | - | - | - |
| Raytheon | User | Inactive | - | - | - | - |
| SiSoft | User | Active | X | X | X | X |
| Synopsys | User | Active | X | X | X | X |
| Teraspeed Labs | General Interest | Inactive | X | X | - | - |
| Xilinx | Producer | Inactive | - | - | - | - |
| ZTE Corp. | User | Inactive | - | - | - | X |
| Zuken | User | Inactive | - | - | X | - |

Criteria for SAE member in good standing:

* Must attend two consecutive meetings to establish voting membership
* Membership dues current
* Must not miss two consecutive meetings

Interest categories associated with SAE standards ballot voting are:

* Users - members that utilize electronic equipment to provide services to an end user.
* Producers - members that supply electronic equipment.
* General Interest - members are neither producers nor users. This category includes, but is not limited to, government, regulatory agencies (state and federal), researchers, other organizations and associations, and/or consumers.